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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of Conveying Part(ies):
Dinesh Chopra

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
Name: Micron Technology, Inc.
Internal Address:

Street Address: 8000 South Federal Way

City: Boise State: ID Zip: 83706

Additional names(s) & address(es) attached: Yes No

11/19/98
JCS51 U.S. PTO
09/189896

3. Nature of conveyance:

Assignment Security Agreement
 Merger Change of Name
 Other

Execution Date: 10/23/98

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: 10/23/98

A. Patent Application No.(s):
09 189896

Additional numbers attached: Yes No

B. Patent No.(s)
40E

Additional numbers attached: Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Mark S. Matkin
Internal Address: Wells, St. John, Roberts,
Gregory & Matkin P.S.
Street Address: 601 W. First Avenue, Ste. 1300
City: Spokane State: WA Zip: 99201-3828

6. Total number of applications and patents involved. 1

7. Total fee (37 CFR 3.41). \$ 40
 Enclosed
 Authorized to be charged to deposit account

8. Deposit account number
23-0925

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To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Mark S. Matkin
Name of Person Signing

Signature

11/19/98
Date

TOTAL NUMBER OF PAGES INCLUDING COVER SHEET, ATTACHMENTS AND DOCUMENT: 4

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PATENT ASSIGNMENT

PARTIES TO THE ASSIGNMENT:

INVENTOR:

Dinesh Chopra

ASSIGNEE:

Micron Technology, Inc.
Corporation of the State of Delaware
8000 South Federal Way
Boise, Idaho 83706-9632

BACKGROUND OF THIS ASSIGNMENT:

INVENTOR has conceived certain new and useful inventions disclosed in a United States patent application titled **A Copper Chemical-Mechanical Polishing Process Using A Fixed Abrasive Polishing Pad And A Copper Layer Chemical-Mechanical Polishing Solution Specifically Adapted For Chemical-Mechanical Polishing With A Fixed Abrasive Pad.**

MICRON TECHNOLOGY, INC. desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

THE PARTIES AGREE AS FOLLOWS:

In consideration of good and valuable consideration, the receipt sufficiency and adequacy of which is hereby acknowledged, INVENTOR hereby sells, assigns and transfers to MICRON TECHNOLOGY, INC. the entire right and interest in the above-identified application executed

1 concurrently with this assignment and to any reissues, renewals, divisions
2 or continuations thereof, and hereby authorizes the Commissioner of
3 Patents and Trademarks to issue such Letters Patent to MICRON
4 TECHNOLOGY, INC. for the sole use of MICRON TECHNOLOGY,
5 INC., its successors or assigns.

6 INVENTOR further agrees to execute, at the request and expense
7 of MICRON TECHNOLOGY, INC. such other formal documents as may
8 be required to fully convey the interest transferred herein and will
9 similarly execute any application papers required for the filing of any
10 division, continuation, renewal or reissue of the patent application or
11 resulting Letters Patent; and will generally do everything necessary or
12 desirable to obtain and enforce proper protection for the invention
13 assigned hereby.

14 INVENTOR further assigns to MICRON TECHNOLOGY, INC. the
15 whole right, title and interest in the inventions disclosed in the
16 application throughout all countries foreign to the United States.
17 MICRON TECHNOLOGY, INC. is hereby authorized to apply for
18 patents relating to the inventions in its own name in countries where
19 such procedure is proper; to claim the benefit of the International
20 Convention; to file and prosecute International Applications relating to
21 the inventions under the Patent Cooperation Treaty; and to file and
22 prosecute applications relating to the inventions under the European
23 Patent Convention. INVENTOR agrees to execute applications relating
24 to the inventions in those countries and under those conventions where

1 it is necessary that the same be executed by the inventor, and to
2 execute assignments of such applications and the resulting Letters Patent
3 to MICRON TECHNOLOGY, INC. as well as all other necessary papers
4 in relation to such applications and Letters Patent.

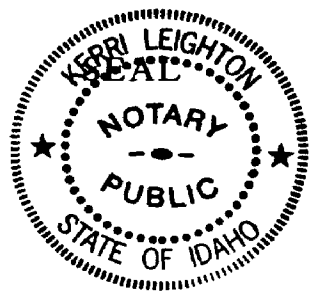
5 INVENTOR further warrants and covenants that no assignment,
6 grant, mortgage, license or other agreement affecting the rights and
7 property herein conveyed has been or will be made to others by the
8 undersigned, and that the full rights to convey the same as herein
9 expressed is possessed by the undersigned.

10 To be binding on the heirs, assigns, representatives and successors
11 of the undersigned and extend to the successors, assigns and nominees
12 of the Assignees.

13 (Signature) *D Chopra* Date: 10/23/98
14 Dinesh Chopra

15 State of Idaho)
16 County of Ada) ss.

17 BEFORE ME, this 23 day of October 1998
18 personally appeared the above-named inventor, to me known to be the
19 person who is described in and who executed the foregoing assignment
instrument and acknowledged to me that he/she executed the same of
his/her own free will for the purpose therein expressed.



21 *Kerri Leighton*
22 Notary or Consular Officer
23 My Commission Expires: 1/9/2002